L Number	Hits	Search T xt	DB	Time stamp
1	2922	(die n ar10 first near10 surfac n ar10 sec nd).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/17 11:26
2	84	((die near10 first near10 surface near10 second).ti,ab,clm.) and ((heat or spreader or slug or heatsink) near5 second near5 surface near5 die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/17 11:14
3	67	(((die near10 first near10 surface near10 second).ti,ab,clm.) and ((heat or spreader or slug or heatsink) near5 second near5 surface near5 die)) and ((heat or spreader or slug or heatsink) near5 second near5 surface near5 die).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/17 11:16
4	33	((((die near10 first near10 surface near10 second).ti,ab,clm.) and ((heat or spreader or slug or heatsink) near5 second near5 surface near5 die)) and ((heat or spreader or slug or heatsink) near5 second near5 surface near5 die).ti,ab,clm.) and (encapsulant or epoxy or resin).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/17 11:16
	30	(((((die near10 first near10 surface near10 second).ti,ab,clm.) and ((heat or spreader or slug or heatsink) near5 second near5 surface near5 die)) and ((heat or spreader or slug or heatsink) near5 second near5 surface near5 die).ti,ab,clm.) and (encapsulant or epoxy or resin).ti,ab,clm.) and ((die near10 first near10 surface near10 second)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/17 11:45
6	0	(substrate near50 surface near50 die near50 first near50 second near50 (heat or heatsink or spreader or slug) near50 (epoxy or resin or encapsulant)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/17 11:48
7	0	(substrate near100 surface near100 die near100 first near100 second near100 (heat or heatsink or spreader or slug) near100 (epoxy or resin or encapsulant)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/17 11:51
3	5	(substrate same surface same die same first same second same (heat or heatsink or spreader or slug) same (epoxy or resin or encapsulant)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/17 11:53
•	122	(heatsink or spreader r slug or h at) n ar5 (dir ctly) near5 (attached or b nded r attach or attaching or b nding or b nd) near5 (di)	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/17 11:56

10	30	((h atsink rspr ader rslug rheat) n ar5	USPAT;	2003/01/17
		(directly) near5 (attached r bonded or	US-PGPUB;	11:58
	·	attach or attaching or bonding or b nd )	EPO; JPO;	
		near5 (di )) and (bga r ball).ti,ab,clm.	DERWENT;	
			IBM_TDB	
11	37	((h at rh atsink or spread ror slug r	USPAT;	2003/01/17
		sink) near5 (wire or wiring) near5 die).clm.	US-PGPUB;	12:02
			EPO; JPO;	
		·	DERWENT;	
			IBM_TDB	
12	13	(((heat or heatsink or spreader or slug or	USPAT;	2003/01/17
		sink) near5 (wire or wiring) near5 die).clm.)	US-PGPUB;	12:01
		and (bga or ball)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	1
13	9	((heat or heatsink or spreader or slug or	USPAT;	2003/01/17
		sink) near10 (wire or wiring) near10 die	US-PGPUB;	12:04
		near10 (attached or bonded)).clm.	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
14	7947	((heat or heatsink or spreader or slug or	USPAT;	2003/01/17
		sink) near10 (attach or attaching or	US-PGPUB;	12:06
		attached or bond or bonding or bonded)	EPO; JPO;	
		near10 (chip or die or ic))	DERWENT;	
			IBM_TDB	
15	608	((heat or heatsink or spreader or slug or	USPAT;	2003/01/17
		sink) near10 (directly or direct) near10	US-PGPUB;	12:08
	•	(attach or attaching or attached or bond or	EPO; JPO;	
		bonding or bonded) near10 (chip or die or	DERWENT;	
		ic))	IBM_TDB	
16	215	(((heat or heatsink or spreader or slug or	USPAT;	2003/01/17
		sink) near10 (directly or direct) near10	US-PGPUB;	12:11
		(attach or attaching or attached or bond or	EPO; JPO;	
		bonding or bonded) near10 (chip or die or	DERWENT;	
		ic))) and (bga or ball)	IBM_TDB	
17	34	((((heat or heatsink or spreader or slug or	USPAT;	2003/01/17
		sink) near10 (directly or direct) near10	US-PGPUB;	12:11
		(attach or attaching or attached or bond or	EPO; JPO;	
		bonding or bonded) near10 (chip or die or	DERWENT;	
		ic))) and (bga or ball)) and (((heat or	IBM_TDB	
		heatsink or spreader or slug or sink) near10		
		(directly or direct) near10 (attach or		
		attaching or attached or bond or bonding or		
		bonded) near10 (chip or die or ic))).ti,ab,clm.		
18	101	((((heat or heatsink or spreader or slug or	USPAT;	2003/01/17
		sink) near10 (directly or direct) near10	US-PGPUB;	12:11
		(attach or attaching or attached or bond or	EPO; JPO;	
	[	bonding or bonded) near10 (chip or die or	DERWENT;	
		ic))) and (bga or ball)) and (((h at or	IBM_TDB	
		heatsink or spr ader or slug or sink) n ar10		
	1	(attach rattaching or attach d rb nd r		
		b nding or b nded) near10 (chip r die r		
		ic))).ti,ab,clm.		

19	53	(((((heat or heatsink rspr ad rorslug or	USPAT;	2003/01/17
1.5	33	sink) n ar10 (dire tly or direct) near10	US-PGPUB;	12:14
		(attach or attaching or attached r bond r	EPO; JPO;	12:14
		b nding or b nd d) n ar10 (chip or di r	DERWENT;	
		ic))) and (bga or ball)) and (((h at or	IBM_TDB	
		h atsink or spr ad r rslug rsink) n ar10	15111_155	
		(attach or attaching or attached or bond or		
		bonding or bonded) near10 (chip or die or		İ
		ic))).ti,ab,clm.) and (bga or ball).ti,ab,clm.		
20	180	(heatsink or slug or spreader or sink or	USPAT;	2003/01/17
		heat).clm. and (bga or ball).ti,ab,clm. and	US-PGPUB;	12:16
		(epoxy or resin or encapsulant).clm. and	EPO; JPO;	12.10
		(wire or wiring or bondwire).clm. and (die or	DERWENT;	
		chip or ic).clm.	IBM_TDB	
21	100	((heatsink or slug or spreader or sink or	USPAT;	2003/01/17
		heat).clm. and (bga or ball).ti,ab,clm. and	US-PGPUB;	12:18
		(epoxy or resin or encapsulant).clm. and	EPO; JPO;	12.10
		(wire or wiring or bondwire).clm. and (die or	DERWENT;	
		chip or ic).clm.) and ((wire or wiring) near10	IBM_TDB	
		(heat or sink or heatsink or spreader or	15155	
		slug))		
22	38	((heatsink or slug or spreader or sink or	USPAT:	2003/01/17
		heat).clm. and (bga or ball).ti,ab,clm. and	US-PGPUB;	12:20
		(epoxy or resin or encapsulant).clm. and	EPO; JPO;	
		(wire or wiring or bondwire).clm. and (die or	DERWENT;	
		chip or ic).clm.) and ((wire or wiring) near10	IBM_TDB	
		(heat or sink or heatsink or spreader or		
		slug)).clm.		
23	24	(((heatsink or slug or spreader or sink or	USPAT;	2003/01/17
		heat).clm. and (bga or ball).ti,ab,clm. and	US-PGPUB;	12:21
		(epoxy or resin or encapsulant).clm. and	EPO; JPO;	
		(wire or wiring or bondwire).clm. and (die or	DERWENT;	
		chip or ic).clm.) and ((wire or wiring) near10	IBM_TDB	
		(heat or sink or heatsink or spreader or	_	
		slug)).clm.) and substrate.clm.		
24	1593	((heat or heatsink or slug or spreader or	USPAT;	2003/01/17
		sink) same (directly or direct) same (die or	US-PGPUB;	12:27
		chip or package or ic) same (epoxy or resin	EPO; JPO;	
		or encasulate or encapsulated or	DERWENT;	
		encapsulating))	IBM_TDB	
25	466	(((heat or heatsink or slug or spreader or	USPAT;	2003/01/17
		sink) same (directly or direct) same (die or	US-PGPUB;	12:28
		chip or package or ic) same (epoxy or resin	EPO; JPO;	
		or encasulate or encapsulated or	DERWENT;	
		encapsulating))) and (cavity or (cavity near	IBM_TDB	
	,	(up or down)) or cavity-up or cavity-down)		
26	209	((((heat or heatsink or slug or spreader or	USPAT;	2003/01/17
		sink) same (directly or direct) same (die or	US-PGPUB;	12:30
		chip or package ric) same (ep xy rresin	EPO; JPO;	
		r encasulate or ncapsulated r	DERWENT;	
		encapsulating))) and (cavity r (cavity n ar	IBM_TDB	
		(up or down)) or cavity-up r cavity-d wn))		
		and (bga r ball)		

27	119	(((((heat rh atsink rslug or spr ader or	USPAT;	2003/01/17
		sink) same (directly r direct) same (die r	US-P PUB;	12:30
		chip r packag or ic) same (ep xy r resin	EPO; JPO;	
		or encasulate or encapsulated r	DERWENT;	
		encapsulating))) and (cavity r (cavity near	IBM_TDB	1
		(up or down)) r cavity-up r cavity-d wn))		
		and (bga or ball)) and (heat or heatsink or		
		spreader or sink or slug).clm.		
28	73	((((((heat or heatsink or slug or spreader or	USPAT;	2003/01/17
		sink) same (directly or direct) same (die or	US-PGPUB;	12:26
ĺ		chip or package or ic) same (epoxy or resin	EPO; JPO;	12.20
ĺ		or encasulate or encapsulated or	DERWENT;	
i		encapsulating))) and (cavity or (cavity near	IBM_TDB	
		(up or down)) or cavity-up or cavity-down))	15111_155	
		and (bga or ball)) and (heat or heatsink or		
		spreader or sink or slug).clm.) and (epoxy or resin or encapsulate or encapsulating or		
20	27	encapsulated).clm.		0000/04/4=
29	57	((((((heat or heatsink or slug or spreader or	USPAT;	2003/01/17
		sink) same (directly or direct) same (die or	US-PGPUB;	12:27
		chip or package or ic) same (epoxy or resin	EPO; JPO;	
		or encasulate or encapsulated or	DERWENT;	
		encapsulating))) and (cavity or (cavity near	IBM_TDB	
		(up or down)) or cavity-up or cavity-down))		
		and (bga or ball)) and (heat or heatsink or		
		spreader or sink or slug).clm.) and (epoxy or		
		resin or encapsulate or encapsulating or		
		encapsulated).clm.) and substrate.clm.		
30	55	(((((((heat or heatsink or slug or spreader or	USPAT;	2003/01/17
		sink) same (directly or direct) same (die or	US-PGPUB;	12:27
Ţ		chip or package or ic) same (epoxy or resin	EPO; JPO;	
		or encasulate or encapsulated or	DERWENT;	
		encapsulating))) and (cavity or (cavity near	IBM_TDB	
		(up or down)) or cavity-up or cavity-down))		
		and (bga or ball)) and (heat or heatsink or		
		spreader or sink or slug).clm.) and (epoxy or		
		resin or encapsulate or encapsulating or		
		encapsulated).clm.) and substrate.clm.) and		
		(wire or wiring)		
31	36	((((((((heat or heatsink or slug or spreader or	USPAT;	2003/01/17
		sink) same (directly or direct) same (die or	US-PGPUB;	12:27
		chip or package or ic) same (epoxy or resin	EPO; JPO;	12.2.
		or encasulate or encapsulated or	DERWENT;	
		encapsulating))) and (cavity or (cavity near	IBM_TDB	
	į	(up or down)) or cavity-up or cavity-down))	15111_156	
		and (bga or ball)) and (heat or heatsink or		
		spreader or sink or slug).clm.) and (epoxy or		
	İ			
		resin or encapsulate or encapsulating or		
		encapsulat d).clm.) and substrate.clm.) and		
		(wire r wiring).clm.	L	

32	1603	((heat rh atsink rslug or spreader rsink	USPAT;	2003/01/17
		or stiffener) same (directly or dir ct) same	US-PGPUB;	12:28
		(di r chip or packag r ic) same (epoxy	EPO; JPO;	
		orr sin rencasulate r ncapsulated or	DERWENT;	
		encapsulating))	IBM_TDB	
33	471	(((h at or heatsink or slug r spread r or	USPAT;	2003/01/17
		sink or stiffener) same (directly or direct)	US-PGPUB;	12:29
		same (die or chip or package or ic) same	EPO; JPO;	
		(epoxy or resin or encasulate or	DERWENT;	
		encapsulated or encapsulating))) and (cavity	IBM_TDB	
		or (cavity near (up or down)) or cavity-up or		
		cavity-down)		
34	210	((((heat or heatsink or slug or spreader or	USPAT;	2003/01/17
<b>J</b> 4	2.0	sink or stiffener) same (directly or direct)	US-PGPUB;	12:30
		same (die or chip or package or ic) same	EPO; JPO;	12.00
		(epoxy or resin or encasulate or	DERWENT;	
		encapsulated or encapsulating))) and (cavity	IBM_TDB	
		or (cavity near (up or down)) or cavity-up or	15156	
		, , , , , , , , , , , , , , , , , , , ,		
25	406	cavity-down)) and (bga or ball)	USPAT:	2003/01/17
35	106	(((((heat or heatsink or slug or spreader or	US-PGPUB;	12:33
		sink or stiffener) same (directly or direct)	· ·	12:33
		same (die or chip or package or ic) same	EPO; JPO;	
		(epoxy or resin or encasulate or	DERWENT;	
		encapsulated or encapsulating))) and (cavity	IBM_TDB	
		or (cavity near (up or down)) or cavity-up or		
		cavity-down)) and (bga or ball)) and (heat or		
		heatsink or spreader or sink or slug or		
		stiffener).ab.clm.		
36	37	((((((heat or heatsink or slug or spreader or	USPAT;	2003/01/17
		sink or stiffener) same (directly or direct)	US-PGPUB;	12:31
		same (die or chip or package or ic) same	EPO; JPO;	
		(epoxy or resin or encasulate or	DERWENT;	
		encapsulated or encapsulating))) and (cavity	IBM_TDB	
		or (cavity near (up or down)) or cavity-up or		
		cavity-down)) and (bga or ball)) and (heat or		
		heatsink or spreader or sink or slug or		
		stiffener).ab.clm.) and ((wire or wiring) and		
		(substrate)).clm.		
37	28	(((((((heat or heatsink or slug or spreader or	USPAT;	2003/01/17
		sink or stiffener) same (directly or direct)	US-PGPUB;	12:31
		same (die or chip or package or ic) same	EPO; JPO;	
		(epoxy or resin or encasulate or	DERWENT;	
		encapsulated or encapsulating))) and (cavity	IBM_TDB	
		or (cavity near (up or down)) or cavity-up or	_	
		cavity-down)) and (bga or ball)) and (heat or		
		heatsink or spreader or sink or slug or	[4]	
		stiffener).ab.clm.) and ((wire or wiring) and		
		(substrate)).clm.) and (epoxy or resin or		
		ncapsulat r ncapsulat d or		
		n apsulating).clm.		

38	1492375	(heat or hatsink rspread rorsink rslug	USPAT;	2003/01/17
		or stiff n r).ab.clm.	US-PGPUB;	12:34
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
39	55686	(h atsink or spr ader r (heat n ar sink) r	USPAT;	2003/01/17
		slug or stiffener).ab.clm.	US-PGPUB;	12:36
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
40	1027	((heatsink or spreader or (heat near sink) or	USPAT;	2003/01/17
		slug or stiffener).ab.clm.) and (epoxy or	US-PGPUB;	12:35
		resin or encapsulate or encapsulated or	EPO; JPO;	12.00
		_		
		encapsulating).clm.	DERWENT;	
			IBM_TDB	0000/04/4=
41	3768	((heatsink or spreader or (heat near sink) or	USPAT;	2003/01/17
		slug or stiffener).ab.clm.) and (epoxy or	US-PGPUB;	12:35
		resin or encapsulate or encapsulated or	EPO; JPO;	ì
		encapsulating).ab.clm.	DERWENT;	
			IBM_TDB	
42	1027	((heatsink or spreader or (heat near sink) or	USPAT;	2003/01/17
		slug or stiffener).ab.clm.) and (epoxy or	US-PGPUB;	12:35
		resin or encapsulate or encapsulated or	EPO; JPO;	
		encapsulating).clm.	DERWENT;	
		choupsulating/ionin	IBM TDB	
43	441	(((heatsink or spreader or (heat near sink) or	USPAT;	2003/01/17
43	441	,	,	12:36
		slug or stiffener).ab.clm.) and (epoxy or	US-PGPUB;	12:30
		resin or encapsulate or encapsulated or	EPO; JPO;	
		encapsulating).clm.) and (epoxy or resin or	DERWENT;	
		encapsulate or encapsulated or	IBM_TDB	
		encapsulating).ab.		
44	343	((((heatsink or spreader or (heat near sink)	USPAT;	2003/01/17
		or slug or stiffener).ab.clm.) and (epoxy or	US-PGPUB;	12:36
		resin or encapsulate or encapsulated or	EPO; JPO;	
		encapsulating).clm.) and (epoxy or resin or	DERWENT;	
		encapsulate or encapsulated or	IBM_TDB	*
		encapsulating).ab.) and (heatsink or	_	
		spreader or (heat near sink) or slug or		
		stiffener).clm.		
45	343	(((((heatsink or spreader or (heat near sink)	USPAT:	2003/01/17
7.5	343	or slug or stiffener).ab.clm.) and (epoxy or	US-PGPUB;	12:36
		, , , , , , , , , , , , , , , , , , , ,		12.50
		resin or encapsulate or encapsulated or	EPO; JPO;	
		encapsulating).clm.) and (epoxy or resin or	DERWENT;	
		encapsulate or encapsulated or	IBM_TDB	
		encapsulating).ab.) and (heatsink or		
		spreader or (heat near sink) or slug or		
		stiffener).clm.) and (heatsink or spreader or		
		(heat near sink) or slug or stiffener).ab.		

46	100	((((((h atsink or spr ad r r (heat near sink)	USPAT;	2003/01/17
		or slug r stiffen r).ab.clm.) and ( poxy or	US-PGPUB;	12:37
		r sin r ncapsulate or encapsulated or	EPO; JPO;	
		ncapsulating).clm.) and (ep xy or resin r	DERWENT:	
		encapsulat or encapsulat d r	IBM_TDB	
		ncapsulating).ab.) and (heatsink or		
		spreader or (heat near sink) or slug or		
		stiffener).clm.) and (heatsink or spreader or		
		(heat near sink) or slug or stiffener).ab.) and		
		(wire or wiring).clm.		
47	47	(((((((heatsink or spreader or (heat near sink)	USPAT;	2003/01/17
		or slug or stiffener).ab.clm.) and (epoxy or	US-PGPUB;	12:37
		resin or encapsulate or encapsulated or	EPO; JPO;	
		encapsulating).clm.) and (epoxy or resin or	DERWENT;	
		encapsulate or encapsulated or	IBM_TDB	
		encapsulating).ab.) and (heatsink or		
		spreader or (heat near sink) or slug or		
		stiffener).clm.) and (heatsink or spreader or		
		(heat near sink) or slug or stiffener).ab.) and		
		(wire or wiring).clm.) and (bga or ball)		
48	19	5977626.URPN.	USPAT	2003/01/17
	.5			13:31
49	3	("A602704"   "5244050"   "5274 <i>4</i> 04"\ 6N	USPAT	2003/01/17
<b>→</b> J	3	("4692791"   "5311059"   "5371404").PN.	USPAI	
		(110-10-4-10-0)		13:35
50	1	("6504723").PN.	USPAT;	2003/01/17
			US-PGPUB;	13:38
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
51	2	("6163458"). <b>PN</b> .	USPAT;	2003/01/17
			US-PGPUB;	13:39
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
52	3	("6400014").PN.	USPAT;	2003/01/17
		(	US-PGPUB;	13:39
			EPO; JPO;	. 5.55
			DERWENT;	
ra		(II.4.C.O.O.T.O.4.II)	IBM_TDB	000010414=
53	2	("4692791"). <b>PN</b> .	USPAT;	2003/01/17
			US-PGPUB;	13:40
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
54	2	("6433420").PN.	USPAT;	2003/01/17
		-	US-PGPUB;	13:41
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
55	1	("6507104").PN.	USPAT;	2003/01/17
<b></b>	•	( 0007 104 ).FR.	US-PGPUB;	13:41
				13.71
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

56	2	("5977626").PN.	USPAT;	2003/01/17
	_	( 0071 020 )	US-PGPUB;	13:44
			EPO; JP ;	
			DERWENT;	
			IBM_TDB	
57	2	("5616957").PN.	USPAT;	2003/01/17
37	_	( 30 10337 ).FR.	US-PGPUB;	13:45
			EPO; JPO;	13.43
			DERWENT;	
			IBM_TDB	
58	2	("EEE262E") BN	USPAT;	2003/01/17
36	2	("5552635").PN.	1	13:45
			US-PGPUB;	13:45
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
75	9	(US-6504723-\$ or US-6163458-\$ or	USPAT	2003/01/17
		US-6400014-\$ or US-4692791-\$ or		13:59
		US-6433420-\$ or US-6507104-\$ or		
		US-5977626-\$ or US-5616957-\$ or		
		US-5552635-\$).did.		
78	0	(("I75 and (") or ("(conducting or conductive)	USPAT;	2003/01/17
		near (adhesive))")).PN.	US-PGPUB;	14:00
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
79	1	((US-6504723-\$ or US-6163458-\$ or	USPAT;	2003/01/17
		US-6400014-\$ or US-4692791-\$ or	US-PGPUB;	14:02
		US-6433420-\$ or US-6507104-\$ or	EPO; JPO;	
		US-5977626-\$ or US-5616957-\$ or	DERWENT;	
		US-5552635-\$).did.) and ((conducting or	IBM_TDB	
		conductive) near (adhesive))		
80	9	((conducting or conductive) near2	USPAT;	2003/01/17
		(adhesive) near2 (heatsink or spreader or	US-PGPUB;	14:06
		slug or stiffener) near2 (chip or die or ic))	EPO; JPO;	
		,	DERWENT;	
			IBM_TDB	
81	5	(((conducting or conductive) near2	USPAT;	2003/01/17
		(adhesive) near2 (heatsink or spreader or	US-PGPUB;	14:06
		slug or stiffener) near2 (chip or die or ic)))	EPO; JPO;	
		and (bga or ball)	DERWENT;	<b>,</b>
		(,	IBM_TDB	
83	5	(((conducting or conductive) near3	USPAT;	2003/01/17
-		(adhesive) near3 (heatsink or spreader or	US-PGPUB;	14:08
		slug or stiffener) near3 (chip or die or ic)))	EPO; JPO;	
		and (bga and ball)	DERWENT;	# **
		(-34 4114 4411)	IBM_TDB	
82	17	((conducting or conductive) near3	USPAT;	2003/01/17
JŁ		(adhesive) near3 (heatsink or spreader or	US-PGPUB;	14:08
	1	· · · · · · · · · · · · · · · · · · ·		17.00
		slug or stiffen r) n ar3 (chip r die r ic))	EPO; JP ;	
			DERWENT;	
	1		IBM_TDB	L

04	40	/IIC CENATOO & IIC C4CO4E0 &	HEDAT	2003/01/17
94	10	(US-6504723-\$ r US-6163458-\$ r US-6400014-\$ or US-4692791-\$ r	USPAT	14:11
		US-6433420-\$ or US-6507104-\$ r		
		US-5977626-\$ or US-5616957-\$ r		
		US-5552635-\$ r US-6008991-\$).did.		
97	0	((US-6504723-\$ or US-6163458-\$ r	USPAT;	2003/01/17
<i>J.</i>		US-6400014-\$ or US-4692791-\$ or	US-PGPUB;	14:11
		US-6433420-\$ or US-6507104-\$ or	EPO; JPO;	
		US-5977626-\$ or US-5616957-\$ or	DERWENT;	
		US-5552635-\$ or US-6008991-\$).did.) and	IBM_TDB	
		(method or process).clm.		
98	33791	(spreader or sink or heatsink or slug or	USPAT;	2003/01/17
		stiffener).ti.	US-PGPUB;	14:12
	:		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
99	24733	((spreader or sink or heatsink or slug or	USPAT;	2003/01/17
		stiffener).ti.) and (spreader or sink or	US-PGPUB;	14:12
		heatsink or slug or stiffener).ab.	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
100	2794	(((spreader or sink or heatsink or slug or	USPAT;	2003/01/17
		stiffener).ti.) and (spreader or sink or	US-PGPUB;	14:12
		heatsink or slug or stiffener).ab.) and	EPO; JPO;	
		(spreader or sink or heatsink or slug or	DERWENT;	
		stiffener).clm.	IBM_TDB	
101	729	((((spreader or sink or heatsink or slug or	USPAT;	2003/01/17
	, 23	stiffener).ti.) and (spreader or sink or	US-PGPUB;	14:19
		heatsink or slug or stiffener).ab.) and	EPO; JPO;	
		(spreader or sink or heatsink or slug or	DERWENT;	
		stiffener).clm.) and (method or process).clm.	IBM_TDB	
102	144	(((((spreader or sink or heatsink or slug or	USPAT;	2003/01/17
		stiffener).ti.) and (spreader or sink or	US-PGPUB;	14:19
	,	heatsink or slug or stiffener).ab.) and	EPO; JPO;	
		(spreader or sink or heatsink or slug or	DERWENT;	
		stiffener).clm.) and (method or	IBM_TDB	
		process).clm.) and (bga or ball)		
103	88	((((((spreader or sink or heatsink or slug or	USPAT;	2003/01/17
		stiffener).ti.) and (spreader or sink or	US-PGPUB;	14:19
		heatsink or slug or stiffener).ab.) and	EPO; JPO;	
		(spreader or sink or heatsink or slug or	DERWENT;	
		stiffener).clm.) and (method or	IBM_TDB	
		process).clm.) and (bga or ball)) and		
		adhesive		
104	72	(((((((spreader or sink or heatsink or slug or	USPAT;	2003/01/17
		stiffener).ti.) and (spreader or sink or	US-PGPUB;	14:20
		heatsink or slug or stiffener).ab.) and	EPO; JPO;	
		(spreader or sink or heatsink or slug or	DERWENT;	
		stiffen r).clm.) and (m thod or	IBM_TDB	
		process).clm.) and (bga r ball)) and		
		adh siv ) and ( p xy or r sin r		
		ncapsulant)		

105	58	(((((((spreader or sink r heatsink or slug r	USPAT;	2003/01/17
		stiffener).ti.) and (spr ader r sink r	US-PGPUB;	14:20
		h atsink or slug r stiff ner).ab.) and	EPO; JPO;	
		(spreader or sink r h atsink r slug r	DERWENT;	
		stiff n r).clm.) and (m th d or	IBM_TDB	
		pr c ss).clm.) and (bga r ball)) and		
		adhesive) and (epoxy or resin or		
		encapsulant)) and substrate		
106	14	((((((((spreader or sink or heatsink or slug or	USPAT;	2003/01/17
		stiffener).ti.) and (spreader or sink or	US-PGPUB;	14:25
		heatsink or slug or stiffener).ab.) and	EPO; JPO;	·
		(spreader or sink or heatsink or slug or	DERWENT;	
		stiffener).clm.) and (method or	IBM_TDB	
		process).clm.) and (bga or ball)) and	_	
		adhesive) and (epoxy or resin or		
		encapsulant)) and substrate) and ((direct or		
		directly) near5 (slug or spreader or sink or		
		heatsink or stiffener) near5 (die or chip or		
		ic))		
107	6	(((((((((spreader or sink or heatsink or slug	USPAT;	2003/01/17
		or stiffener).ti.) and (spreader or sink or	US-PGPUB;	14:25
		heatsink or slug or stiffener).ab.) and	EPO; JPO;	
		(spreader or sink or heatsink or slug or	DERWENT;	
		stiffener).clm.) and (method or	IBM_TDB	
		process).clm.) and (bga or ball)) and		
		adhesive) and (epoxy or resin or		
		encapsulant)) and substrate) and ((direct or		
		directly) near5 (slug or spreader or sink or		
		heatsink or stiffener) near5 (die or chip or		
		ic))) and (direct or directly).clm.		